PCI-GPIB Specifications

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PCI-GPIB Specifications

Definitions

Warranted specifications describe the performance of a model under stated operating conditions and are covered by the model warranty.

Characteristics describe values that are relevant to the use of the model under stated operating conditions but are not covered by the model warranty.

- **Typical** specifications describe the performance met by a majority of models.
- **Nominal** specifications describe an attribute that is based on design, conformance testing, or supplemental testing.

Specifications are **Typical** unless otherwise noted.

Performance

GPIB	
3-wire	up to 1536 kbytes/s
HS488	up to 7885 kbytes/s

Power Requirements

PCI-GPIB/TNT4882C[1]	
+3.3 V	121 mA, Typical; 182 mA, Maximum
+5 V	300 mA, Typical; 450 mA, Maximum
PCI-GPIB/TNT5004[2]	

+5 V	150 mA, Maximum
VIO	5 mA, Maximum
PCI-GPIB/LP (Low Profile)[3]	
+5 V	300 mA, Typical; 450 mA, Maximum

Physical Characteristics

Dimensions	
PCI-GPIB/TNT4882C	13.3 cm × 10.7 cm (5.25 in. × 4.20 in.)
PCI-GPIB/TNT5004	12 cm × 6.44 cm (4.72 in. × 2.54 in.)
PCI-GPIB/LP	12 cm × 6.44 cm (4.87 in. × 2.54 in.)
Connector	
GPIB	IEEE 488 24-pin connector (The PCI-GPIB/LP uses a special cable to convert between the Micro D-Sub connector of the board and the GPIB connector.)
PCI	Universal

Environment

Operating ambient temperature	0 °C to 55 °C (Tested in accordance with IEC 60068-2-1 and IEC 60068-2-2.)
Operating relative humidity	10% to 90%, noncondensing (Tested in accordance with IEC 60068-2-56.)

Storage ambient temperature	-20 °C to 70 °C (Tested in accordance with IEC 60068-2-1 and IEC 60068-2-2.)
Storage relative humidity	5% to 95%, noncondensing (Tested in accordance with IEC 60068-2-56.)